



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-03-29
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH310UFY	AB6Y*S86T2AR	A	BO2A	2013-03-29
Amount		UoM	Unit type	ST ECOPACK Grade
50.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
SOJ	3.75 - 4.3 - 0.98	2	J bend
Comment			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList :REACH-18 June 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AB6Y*586T2AR					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.89	mg	supplier	die	Silicon (Si)	7440-21-3		1.798	mg	951323	35960
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.054	mg	28571	1080
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.013	mg	6878	260
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.006	mg	3175	120
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	529	20
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	1587	60
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.015	mg	7937	300
Leadframe	Copper & its alloys	19.01	mg	supplier	alloy	Copper (Cu)	7440-50-8		18.985	mg	998685	379700
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.009	mg	473	180
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.016	mg	842	320
Soft solder	Solder	1.822	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.74	mg	954995	34800
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.046	mg	25247	920
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.036	mg	19759	720
Bonding wire	Other inorganic materials	0.145		supplier	wire	Copper (Cu)	7440-50-8		0.145	mg	1000000	2900
encapsulation	Other inorganic materials	26.403	mg	supplier	mold compound	Silica, vitreous	60676-86-0		23.103	mg	875014	462060
encapsulation				supplier	mold compound	Epoxy Resin	85954-11-6		1.056	mg	39995	21120
encapsulation				supplier	mold compound	Epoxy resin	Proprietary		1.056	mg	39995	21120
encapsulation				supplier	mold compound	Phenol Resin	26834-02-6		1.056	mg	39995	21120
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.132	mg	4999	2640
connections coating	Solder	0.73	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.73	mg	1000000	14600